

A Large TPC Prototype for an ILC Detector

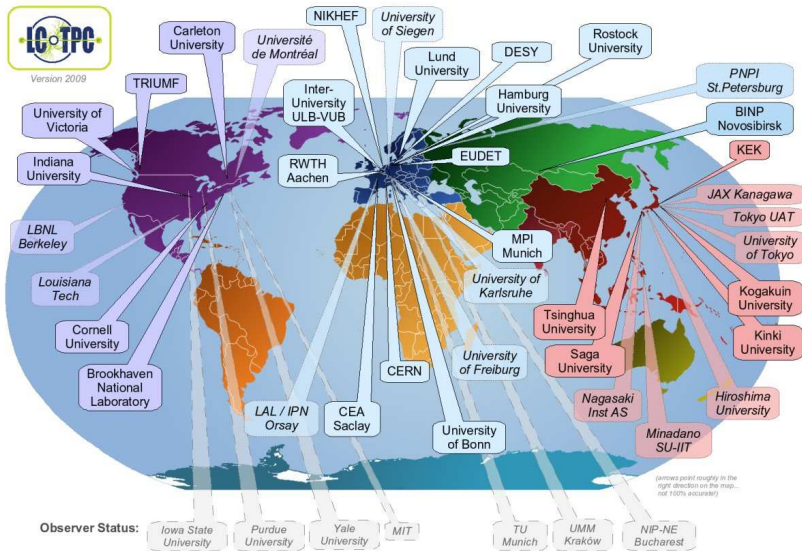
Peter Schade

on behalf of the LCTPC Collaboration

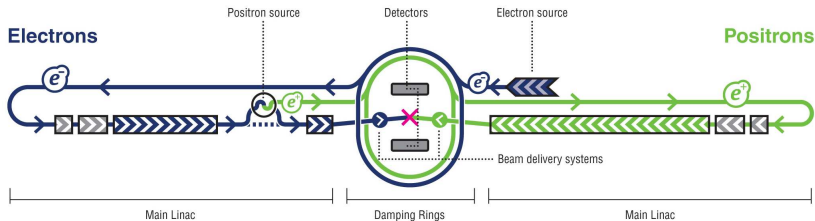
DESY Hamburg

16th February 2010

The LCTPC collaboration



Future e^+e^- Linear Collider

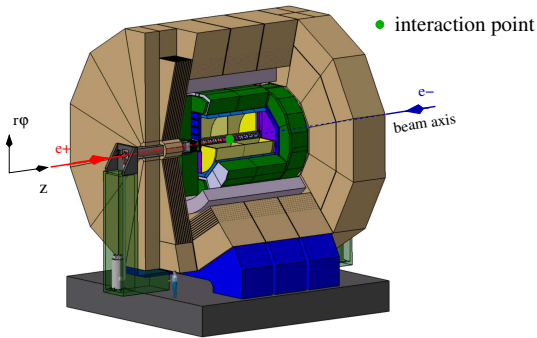


International Linear Collider - ILC

- e^+e^- collider @ $\sqrt{s} = 500$ GeV (upgradeable to 1 TeV)
- luminosity: $\mathcal{L} = 2 \cdot 10^{34} \text{ s}^{-1} \text{ cm}^{-2} \rightarrow 500 \text{ fb}^{-1}$ in four years
- construction could start around 2015

- Compact Linear Collider CLiC with up to $\sqrt{s} = 3$ T
→ technical feasibility to be demonstrated

ILD Detector Concept

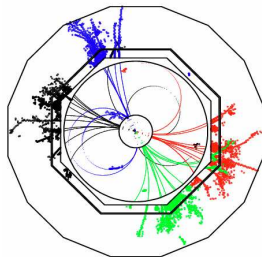


Optimized for Particle Flow

- 3.5 T solenoid with highly granulated HCAL and ECAL inside
- large Time Projection Chamber
- silicon vertex detectors
- slightly inhomogeneous magnetic field (Anti - DiD)

Why a TPC at a Linear Collider

- Particle Flow is believed to be the optimal reconstruction scheme for expected physics signatures at ILC energies
 - requires tracking with highest precision and efficiency
 - robust identification of every particle, even in jets
- a TPC is well suited for Particle Flow
 - robust tracking - up to 200 space points per track (ILD)
 - TPC is robust towards backgrounds
 - dE/dx -measurement input to particle identification
 - TPC has a low material budget

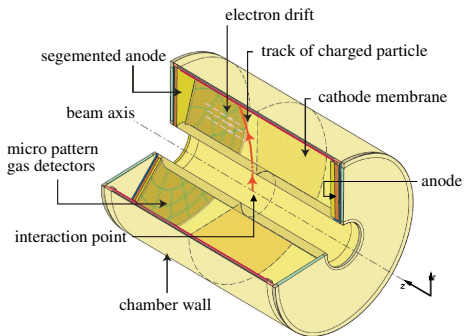


Requirements to a LC TPC

- Particle Flow reconstruction defines stringent requirements to all subdetectors
- for the TPC:

Requirements to TPC (ILD)

- size: $L = 4.3 \text{ m}$ - $d = 3.6 \text{ m}$
- $\sigma_{\perp}^{\text{point}} \leq 100 \mu\text{m}$
- low material budget
 - 1% X_0 inner wall
 - 4% X_0 to outer wall
 - 15% X_0 endcap
- operation in DID field



⇒ performance about ten times better compared to previous TPCs

- LCTPC collaboration aims at the development of the TPC of a LC collider detector
- performance goals require substantial improvements of traditional readout techniques
 - new technique: readout with micro pattern gas detectors

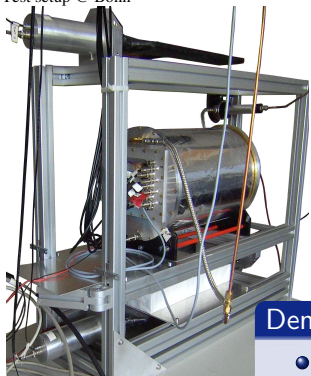
R&D phases

- 1 Demonstration phase - Prospect studies:
 - operation of MPGD readout in small/medium prototypes
 - demonstration of feasibility
- 2 Consolidation phase - Technical studies:
 - development of large scale readout structures (ILD module)
 - operation techniques to cope with inhomogeneous B-field
- 3 Construction phase - Build the ILD TPC

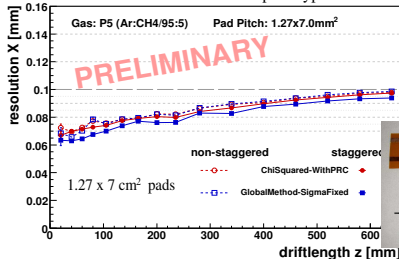
MPGD based TPC readout: Prospect Studies

- small prototypes: diameter ≤ 30 cm - drift length ≤ 80 cm

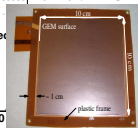
Test setup @ Bonn



Resolution Measurement with DESY prototype



10x10 cm² GEM



Demonstration Phase

- Pad - Pixel readout \Leftrightarrow GEMs - Micromegas
- $\sigma_{\perp} \lesssim 100 \mu\text{m}$ measured
→ for drift lengths of up to 60 cm

\Rightarrow TPC with MPGD readout can reach $\sigma_{\perp} \leq 100 \mu\text{m}$

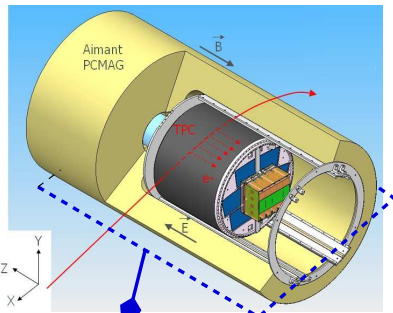
- for the development of large scale MPGD readout structures
 - Large TPC prototype required with diameter $\mathcal{O}(1\text{m})$
 - magnet with inhomogeneous and measured field
 - test beam with external reference detectors
- TPC R&D setup installed at DESY e^- test beam
 - within the EUDET program
- superconducting magnet (PCMAG)
- silicon tracking detectors
- Large Prototype (LP) - consisting of
 - field cage with cathode
- anode end plate for LP constructed within LCTPC collaboration



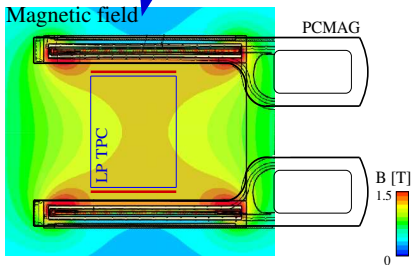
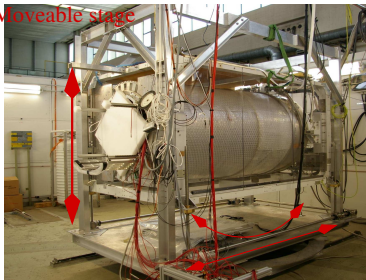
Large TPC Prototype: Testbeam Setup

EUDET setup for TPC R&D

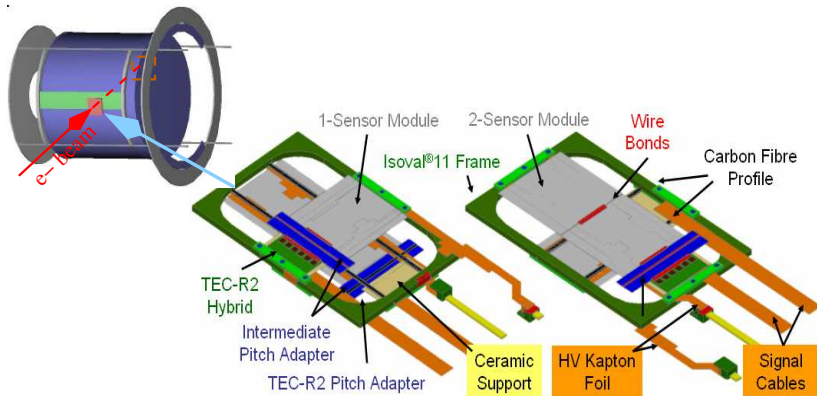
- PCMAG with $B \leq 1.25$ T
- bore diameter: 85 cm
- LP support structure
- Test Beam e^- with $1 \text{ GeV} \leq E_{\text{beam}} \leq 6 \text{ GeV}$



Moveable stage



Testbeam Setup - Silicon Tracking detectors



- 2 layers of Pixel modules with $20 \mu\text{m}$ spacial resolution
- two unbiased points along the trajectory inside PCMAG
→ for the development of TPC reconstruction algorithms in inhomogeneous magnetic fields

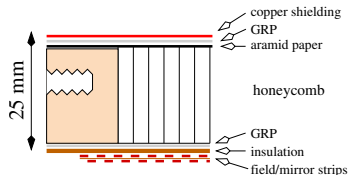
Large TPC Prototype: Field Cage



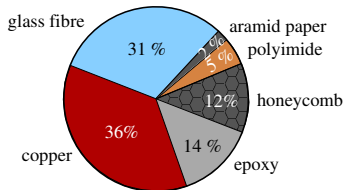
LP Field Cage Parameter

- $L=61\text{ cm}$ - $d_{\text{inner}} = 72\text{ cm}$
- up to 25 kV at the cathode drift field $\rightarrow E \approx 350\text{ V/cm}$

\rightarrow structure made from composite materials



\rightarrow material budget: 1.24 % X_0



\Rightarrow 1 % X_0 per wall within reach

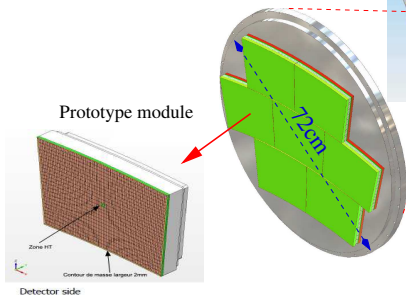
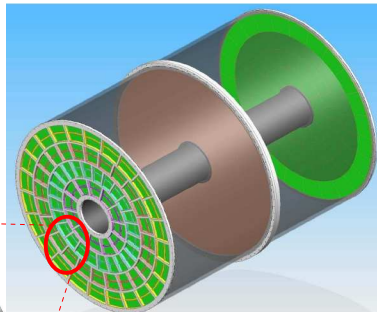
Large TPC Prototype: Anode Endplate

Modular Enplate

- first endplate for the LP made from Al
- 7 module windows
→ size 22×17 cm

→ D. Peterson, U. Cornell

TPC @ Linear Collider Detector



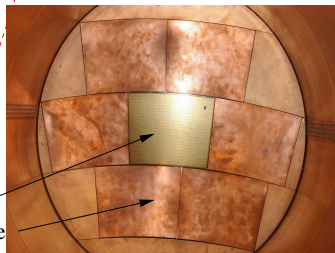
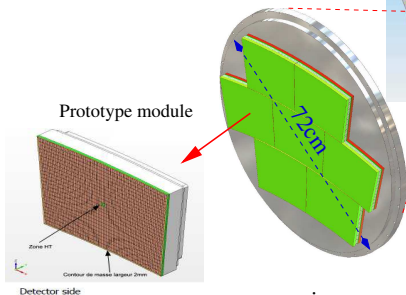
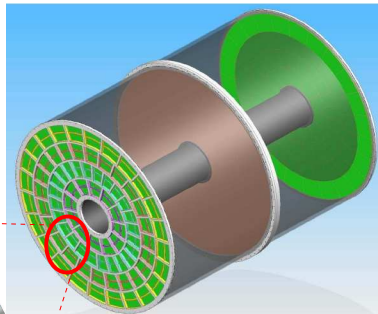
Large TPC Prototype: Anode Endplate

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TPC @ Linear Collider Detector



micromegas
blind module



Testbeam with Micromegas Module

Micromegas Module

- 24 row with 72 pads each
 $3.2 \times 7 \text{ mm}^2$
- resistive foil / carbon loaded kapton ($1 \text{ M}\Omega/\text{sq}$)
→ charge spreading over pads
- AFTER electronics (T2K)

→ P. Colas, CEA Saclay M. Dixit, Carleton U.

Surface resistivity $\sim 1 \text{ M}\Omega/\square$

25 μm Al/Si coated mylar

50 μm THICK
ADHESIVE
LAYER

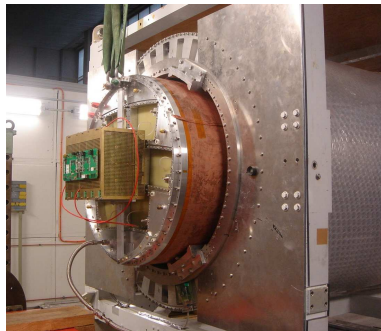
READOUT
PADS

READOUT
PCB

DETAIL A



Peter Schade, Large TPC Prototype

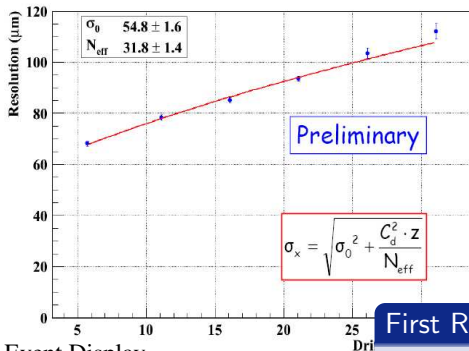


VCI Vienna, 16-02-2010

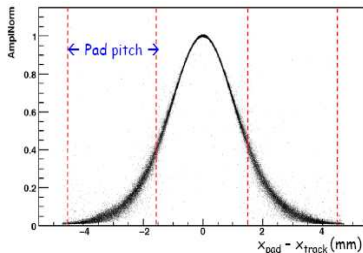
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Testbeam with Micromegas Module

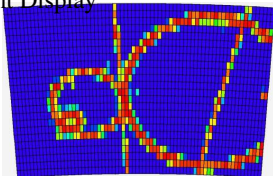
- Resolution at $z=0$: $\sigma_0 = 54.8 \pm 1.6 \mu\text{m}$ with 2.7-3.2 mm pads ($w_{\text{pad}}/55$)
- Effective number of electrons: $N_{\text{eff}} = 31.8 \pm 1.4$ consistent with expectations



Charge spread over pads



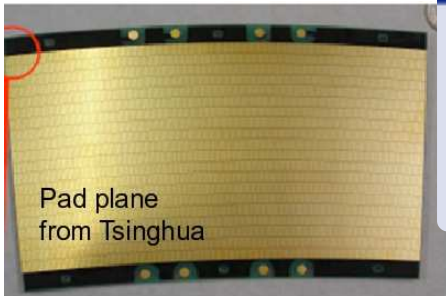
Event Display



First Results (Micromegas module)

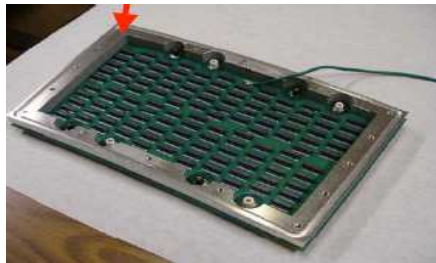
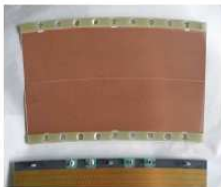
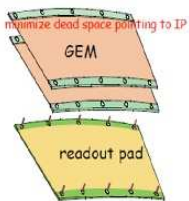
- setup: 5 GeV e^- - $B = 1$ T
→ $\sigma_{\perp}(z = 0) \approx 55 \mu\text{m}$
→ $N_{\text{eff}} = 31.8 \pm 1.4$
- charge spread over 2 - 3 pads

Testbeam with GEM Module

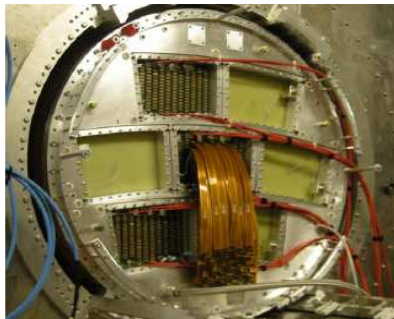


GEM module

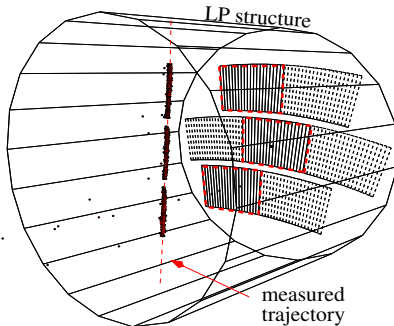
- $1.2 \times 5.4 \text{ mm}^2$ pads - staggered
- 28 pad rows (176-192 pads/row)
- about 5000 ch. per module
- 6 layer PCB board
- stretched mounting of GEMs



Testbeam with GEM Module



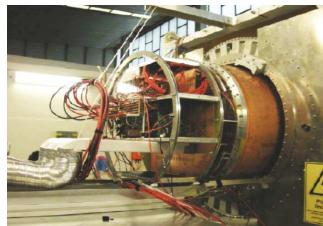
Event display with three modules



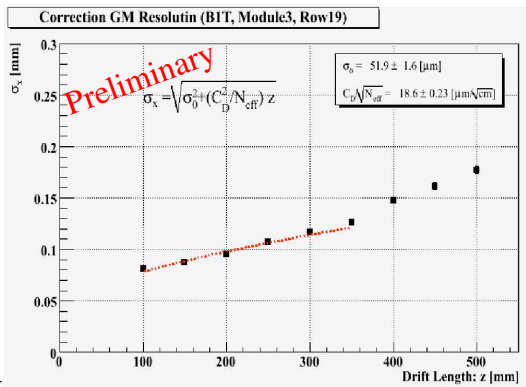
Readout Electronics

- 3 modules operated
→ in total 3200 channels used
- electronics based on the ALTRO chip (ALICE)

→ L. Joensuu, LUND U.



Testbeam with GEM Module

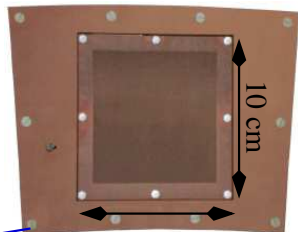
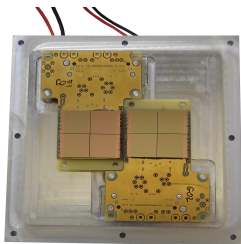


First Results (GEM modules)

- res. parametrized as $\sigma_{\perp} = \sqrt{\sigma_0^2 + D^2 / N_{\text{eff}} \cdot z}$
 $\rightarrow D / \sqrt{N_{\text{eff}}} = 18.5 \pm 0.2 \mu\text{m} / \sqrt{\text{cm}} - \sigma_0 = 51.9 \pm 1.6 \mu\text{m}$

\Rightarrow GEM and Micromegas module show similar performance

GEM Structure & Timepix



anode plane

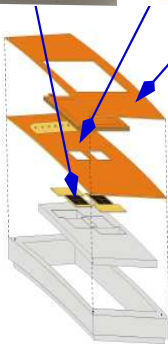
GEMs

readout plane

quad-boards

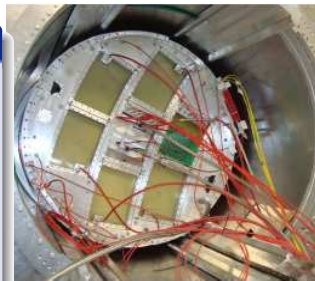
reinforcement of
anode plane

redframe



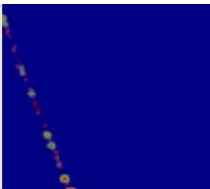
Timepix Module

- eight chips
 $1.4 \times 1.4 \text{ cm}^2$ each
- two quad boards
- $55 \times 55 \mu\text{m}^2$ pixel
- 65000 ch. per chip
→ total: $500 \cdot 10^3$

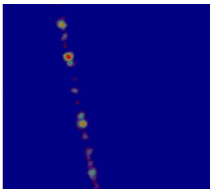


GEM Structure & Timepix

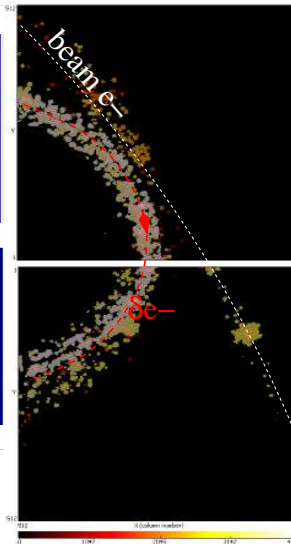
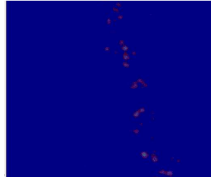
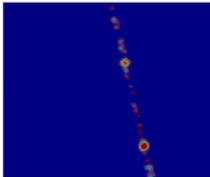
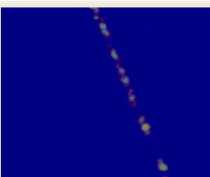
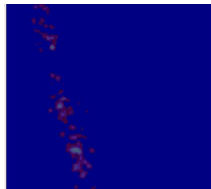
4 cm drift



10 cm drift



40 cm drift

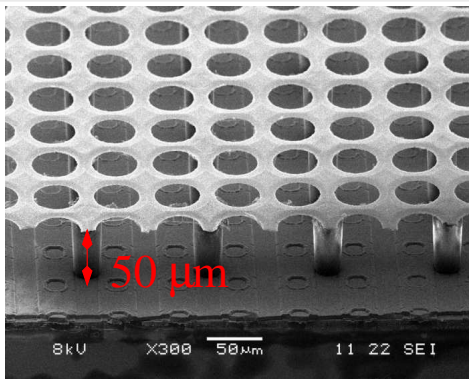
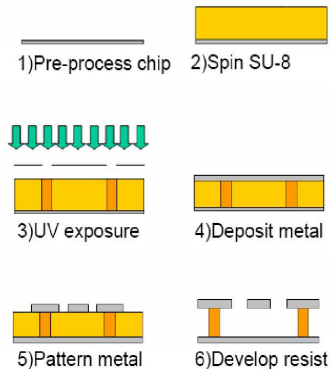


- finest granularity for a TPC readout so far
 - single cluster detection
 - clear identification of δ -electrons possible
 - cluster counting to improve dE/dx -measurement

→ analysis of testbeam data ongoing



InGrid technology



InGrid Chip

- produced in CMOS technology
→ silicon pixel chip : 1 μm AL grid 50 μm pillars
- one hole per pixel and very flat surface

- LCPTPC collaboration performs R&D work for a TPC at a future e^+e^- linear collider
 - large TPC prototype built and commissioned
 - part of comprehensive setup for TPC R&D @ DESY
- GEMs and Micromegas are under investigation for the read out of an LC TPC
 - with standard pad or silicon pixel readout
- test beam campaigns in 2009 with both technologies
 - data analysis ongoing
 - first results look very promising
- further testbeam campaigns in 2010
 - 10.000 channels of ALTRO electronics for 3 GEM modules
 - up to seven Micromegas modules with AFTER electronics
 - combination with silicon tracking detectors